

## Product Change Notification - JAON-04PFPM024 [\(Printer Friendly\)](#)

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<b>Date:</b>	31 Aug 2016
<b>Product Category:</b>	SMSC
<b>Notification subject:</b>	CCB 2518 Final Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 TSMC wafer technology available in 36L VQFN package at ANAC assembly site.
<b>Notification text:</b>	<b>PCN Status:</b> Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 TSMC wafer technology available in 36L VQFN package at ANAC assembly site.

**Pre Change:**

Palladium coated copper wire (PdCu) bond wire

**Post Change:**

Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	ANAC assembly site	ANAC assembly site
<b>Wire material</b>	PdCu wire	CuPdAu wire
<b>Die attach material</b>	8290	8290

<b>Molding compound material</b>	G700	G700
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

September 30, 2016 (date code: 1640)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	March 2016					->	August 2016				September 2016				
WW	09	10	11	12	13		32	33	34	35	36	37	38	39	40
Initial PCN Issue Date		X													
Qual Report Availability											X				
Final PCN Issue Date											X				
Estimated Implementation Date															X

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**March 10, 2016:** Issued initial notification.

**August 31, 2016:** Issued final notification. Attached qualification report. Revised estimated first ship date from June 30, 2016 to September 30, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-04PFPM024\\_Qual\\_Report.pdf](#)  
[PCN\\_JAON-04PFPM024\\_Affected CPN.pdf](#)  
[PCN\\_JAON-04PFPM024\\_Affected CPN.xls](#)

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